

Additional Assembly Site

Mobile DiskOnChip Plus 9x12 FBGA 256Mbit

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Description

The AMKOR Japan fab assembly facility has been selected as an additional assembly facility for Mobile DiskOnChip Plus, manufactured by Toshiba. Until now, Mobile DiskOnChip Plus has been assembled at the Yokkaichi Toshiba Electronics (YTE) facility in Japan only. Starting in April 2004, Mobile DiskOnChip Plus will be assembled either at AMKOR or YTE in Japan.

There is no other change in the Mobile DiskOnChip Plus manufacturing and testing process. Wafers will continue to be manufactured at YTE, and testing will be done at Power Tech Technology (PTI).

Ordering Information

The following product is affected:

Product	Form Factors	Capacity (MB)	Ordering Information
Mobile DiskOnChip Plus	9x12 FBGA	32MByte/256Mbit	MD3831-D32-V3-X MD3831-D32-V3-X-P

Reason for Change

A new assembly site is being added to address the growing market demand. This step will provide additional flexibility and enable M-Systems to respond to customer needs.

Timetable

Products will be assembled at the AMKOR site according to the following schedule:

Product	Ordering Information	Schedule
Mobile DiskOnChip Plus 32MByte/256Mbit	MD3831-D32-V3-X	April 2004
Mobile DiskOnChip Plus 32MByte/256Mbit, Pb-free	MD3831-D32-V3-X-P	

Note: Samples will be available as of March 2004

Compatibility

The products assembled in the new facility are fully hardware and software compatible with the existing products.

Quality Assurance Procedure

Overall responsibility for quality assurance and quality control procedures will remain under the auspices of YTE in Japan. M-Systems and Toshiba are working closely to ensure a smooth addition of the alternative assembly facility. The following actions will be implemented:

- Correlation testing between products that have been assembled at different sites (YTE and AMKOR).
- Functional testing by both M-Systems and Toshiba
- Long-term reliability testing
- Extended monitoring of the first lots manufactured at the new assembly site

How to Contact Us

Please contact your M-Systems representative or visit the DiskOnChip web page on the M-Systems website (www.m-sys.com) for any further information or assistance.

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